

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Tsai-Wei Wu	12/06/2005
RECEIVING PARTY DATA	
Name:	Hitachi Global Storage Technologies Netherlands BV
Street Address:	Locatellikade 1
Internal Address:	Parnassustoren
City:	1076 AZ Amsterdam
State/Country:	NETHERLANDS
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12258767
CORRESPONDENCE DATA	
Fax Number:	(512)472-9123
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	713-223-2300
Email:	robyn.pyle@bgllp.com
Correspondent Name:	BRACEWELL & GIULIANI LLP
Address Line 1:	PO BOX 61389
Address Line 4:	HOUSTON, TEXAS 77208-1389
ATTORNEY DOCKET NUMBER:	HSJ920050254US2
NAME OF SUBMITTER:	Michael E. Noe, Jr.
Total Attachments: 1 source=Assignment#page1.tif	

CH \$40.00 12258767

ASSIGNMENT

Whereas, I,

(1) Tsai-Wei Wu of San Jose, Santa Clara County, California,

have invented certain improvements in

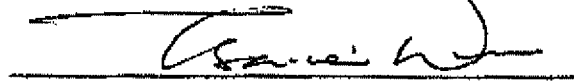
**SYSTEM, METHOD, AND APPARATUS FOR MEMBRANE, PAD, AND STAMPER
ARCHITECTURE FOR UNIFORM BASE LAYER AND NANOIMPRINTING**

and executed, respectively, a United States patent application therefor on (Date Inventor Signed Declaration) (1) 12/06/2005, 2005.

Whereas, Hitachi Global Storage Technologies Netherlands B.V., having a place of business at Locatellikade 1, Parnassustoren, 1076 AZ Amsterdam, The Netherlands, (hereinafter called HITACHI), desires to acquire the entire right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, we, the above named, hereby sell, assign, and transfer to HITACHI, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patent granted upon the invention set forth in said application to HITACHI, its successors and assigns; and we hereby agree that HITACHI may apply for foreign Letters Patent on said invention and we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by HITACHI.

(1) Signed at San Jose, CA on Dec. 6, 2005.



TSAI-WEI WU